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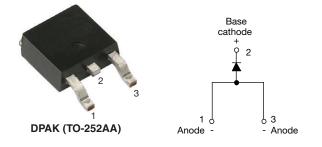
RoHS

COMPLIANT

HALOGEN

FREE

Surface Mount Fast Soft Recovery Rectifier Diode, 8 A



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SHA

PRIMARY CHARACTERISTICS						
I _{F(AV)}	8 A					
V _R	1000 V, 1200 V					
V _F at I _F	1.3 V					
I _{FSM}	150 A					
t _{rr}	80 ns					
T _J max.	150 °C					
Snap factor	0.6					
Package	DPAK (TO-252AA)					
Circuit configuration	Single					

FEATURES

- Glass passivated pellet chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Output rectification and freewheeling diode in inverters, choppers and converters
- Input rectifications where severe restrictions on conducted EMI should be met

DESCRIPTION

The VS-8EWF..S-M3 fast soft recovery rectifier series has been optimized for combined short reverse recovery time, low forward voltage drop and low leakage current.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

MAJOR RATINGS AND CHARACTERISTICS								
SYMBOL	CHARACTERISTICS	VALUES	UNITS					
I _{F(AV)}	Sinusoidal waveform	8	A					
V _{RRM}		1000/1200	V					
I _{FSM}		150	А					
V _F	8 A, T _J = 25 °C	1.3	V					
t _{rr}	1 A, 100 A/µs	80	ns					
TJ	Range	-40 to +150	°C					

VOLTAGE RATINGS									
PART NUMBER	V _{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V _{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I _{RRM} AT 150 °C mA						
VS-8EWF10S-M3	1000	1100	4						
VS-8EWF12S-M3	1200	1300	4						

ABSOLUTE MAXIMUM RATINGS								
PARAMETER SYMBOL TEST CONDITIONS VALUES UNITS								
Maximum average forward current	I _{F(AV)}	T_{C} = 96 °C, 180° conduction half sine wave	8					
Maximum peak one cycle	I _{FSM}	10 ms sine pulse, rated V _{RRM} applied	125	А				
non-repetitive surge current		10 ms sine pulse, no voltage reapplied	150	1				
Maximum I ² t for fusing	l ² t	10 ms sine pulse, rated V _{RRM} applied	78	A ² s				
Maximum - t for fusing	1-1	10 ms sine pulse, no voltage reapplied 110		A-S				
Maximum I ² √t for fusing	l²√t	t = 0.1 ms to 10 ms, no voltage reapplied	1100	A²√s				

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ELECTRICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CO	NDITIONS	VALUES	UNITS				
Maximum forward voltage drop	V _{FM}	8 A, T _J = 25 °C		1.3	V				
Forward slope resistance	rt	T.I = 150 °C		25.6	mΩ				
Threshold voltage	V _{F(TO)}	1J = 150 C		0.93	V				
Maximum reverse leakage current		T _J = 25 °C	V - Retad V	0.1	mA				
Maximum reverse leakage current	IRM	T _J = 150 °C	$V_R = Rated V_{RRM}$	4	ША				

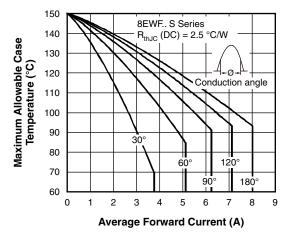
RECOVERY CHARACTERISTICS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	· •				
Reverse recovery time	t _{rr}	I _F at 8 A _{pk}	270	ns	I _{FM}				
Reverse recovery current	I _{rr}	25 A/µs	4.2	А	$I = \frac{t_{rr}}{t_a + t_b}$				
Reverse recovery charge	Q _{rr}	T _J = 25 °C	1	μC					
Snap factor	S		0.6						

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS				
Maximum junction and storage temperature range	T _J , T _{Stg}		-40 to +150	°C				
Maximum thermal resistance, junction to case	R _{thJC}	DC operation	2.5	°C/W				
Typical thermal resistance, junction to ambient (PCB mount)	R _{thJA} ⁽¹⁾		50	C/W				
Approximate weight			1	g				
Approximate weight			0.03	oz.				
Marking davias			8EWF10S					
Marking device		Case style DPAK (TO-252AA)	8EWF12S					

Note

⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μm) copper 40 °C/W For recommended footprint and soldering techniques refer to application note #AN-994

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Fig. 1 - Current Rating Characteristics

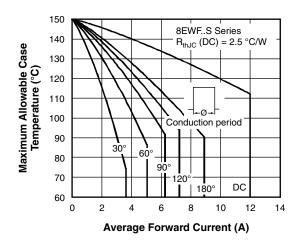


Fig. 2 - Current Rating Characteristics

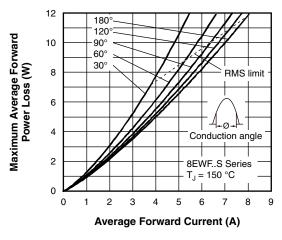


Fig. 3 - Forward Power Loss Characteristics

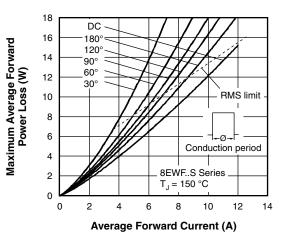


Fig. 4 - Forward Power Loss Characteristics

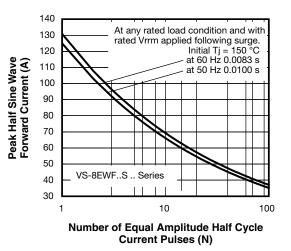


Fig. 5 - Maximum Non-Repetitive Surge Current

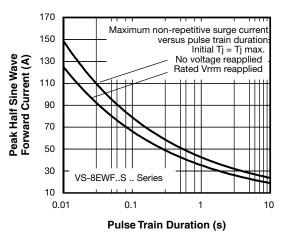


Fig. 6 - Maximum Non-Repetitive Surge Current

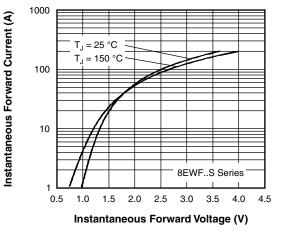
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Fig. 7 - Forward Voltage Drop Characteristics

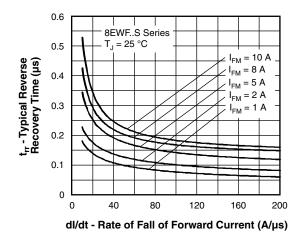


Fig. 8 - Recovery Time Characteristics, $T_J = 25 \ ^{\circ}C$

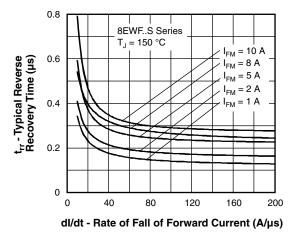
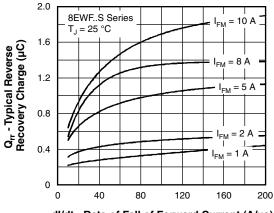


Fig. 9 - Recovery Time Characteristics, $T_J = 150 \ ^\circ C$



dl/dt - Rate of Fall of Forward Current (A/µs)

Fig. 10 - Recovery Charge Characteristics, T_J = 25 °C

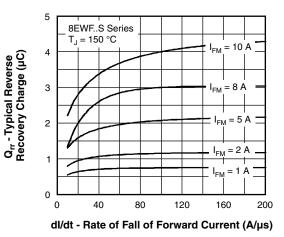


Fig. 11 - Recovery Charge Characteristics, $T_J = 150 \ ^{\circ}C$

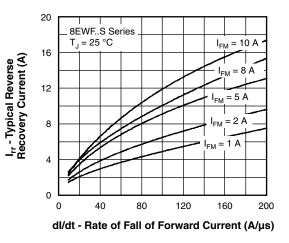


Fig. 12 - Recovery Current Characteristics, $T_J = 25 \ ^{\circ}C$

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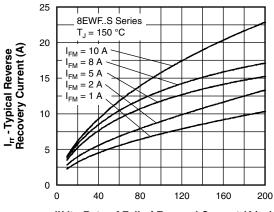
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dl/dt - Rate of Fall of Forward Current (A/µs)

Fig. 13 - Recovery Current Characteristics, T_J = 150 °C

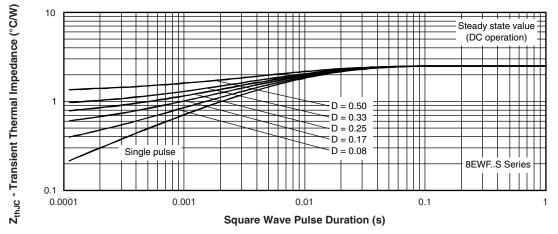


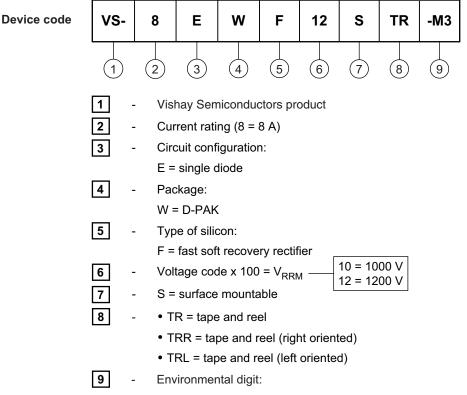
Fig. 14 - Thermal Impedance Z_{thJC} Characteristics

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ORDERING INFORMATION TABLE

SHA



-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)								
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION					
VS-8EWF10S-M3	75	3000	Antistatic plastic tubes					
VS-8EWF10STR-M3	2000	2000	13" diameter reel					
VS-8EWF10STRL-M3	3000	3000	13" diameter reel					
VS-8EWF10STRR-M3	3000	3000	13" diameter reel					
VS-8EWF12S-M3	75	3000	Antistatic plastic tubes					
VS-8EWF12STR-M3	2000	2000	13" diameter reel					
VS-8EWF12STRL-M3	3000	3000	13" diameter reel					
VS-8EWF12STRR-M3	3000	3000	13" diameter reel					

LINKS TO RELATED DOCUMENTS						
Dimensions www.vishay.com/doc?95627						
Part marking information	www.vishay.com/doc?95176					
Packaging information	www.vishay.com/doc?95033					
SPICE model	www.vishay.com/doc?97057					

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D-PAK (TO-252AA) "M"

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES		S SYMBOL		NOTES		MILLIN	IETERS	INC	HES	NOTES
STNIDUL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STIVIDUL	MIN.	MAX.	MIN.	MAX.	NOTES			
А	2.18	2.39	0.086	0.094			е	2.29	BSC	0.090	BSC				
A1	-	0.13	-	0.005			Н	9.40	10.41	0.370	0.410				
b	0.64	0.89	0.025	0.035			L	1.40	1.78	0.055	0.070				
b2	0.76	1.14	0.030	0.045			L1	2.74	BSC	0.108	REF.				
b3	4.95	5.46	0.195	0.215	3		L2	0.51	BSC	0.020	BSC				
с	0.46	0.61	0.018	0.024			L3	0.89	1.27	0.035	0.050	3			
c2	0.46	0.89	0.018	0.035			L4	-	1.02	-	0.040				
D	5.97	6.22	0.235	0.245	5		L5	1.14	1.52	0.045	0.060	2			
D1	5.21	-	0.205	-	3		Ø	0°	10°	0°	10°				
E	6.35	6.73	0.250	0.265	5		Ø1	0°	15°	0°	15°				
E1	4.32	-	0.170	-	3		Ø2	25°	35°	25°	35°				

Notes

⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994

⁽²⁾ Lead dimension uncontrolled in L5

⁽³⁾ Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad

(4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip

(5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

⁽⁶⁾ Dimension b1 and c1 applied to base metal only

⁽⁷⁾ Datum A and B to be determined at datum plane H

⁽⁸⁾ Outline conforms to JEDEC[®] outline TO-252AA



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